



Product Change Notification

Change Notification #: 115206 - 00
Change Title: Intel® Dual Band Wireless-AC 3160 and Intel® Dual Band Wireless-N 3160 SKUs: 3160.HMWG; 3160.HMWGB; 3160.NGWG; 3160.HMWG.R; 3160.HMWGBR; 3160.NGWGB.R; 3160.HMWNBG; 3160.NGWNBG; 3160.NGWG.R; 3160.HMWGB.R; 3160.NGWG.B; 3160.NGWGBR, PCN 115206-00, Transport Media, Clamshell Update
Date of Publication: December 22, 2016

Key Characteristics of the Change:
Transport Media

Forecasted Key Milestones:

| | |
|---|--------------|
| Date Customer Must be Ready to Receive Post-Conversion Material: | Jan 13, 2017 |
|---|--------------|

Description of Change to the Customer:

The Intel® Dual Band 3160 SKUs listed in the products affected table below will undergo the following change:

- Addition of the Korea Recycle Logo to Clamshell packaging



Customer Impact of Change and Recommended Action:

The clamshell change does not affect the functionality of the product. Customers should be aware of the changes and take any necessary steps to insure no impact for their receiving and processing of the product in their manufacturing.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

| Product Code | MM# | TA |
|--------------|--------|------------|
| 3160.HMWG | 923263 | H14634-006 |
| 3160.NGWG | 923265 | H14636-007 |
| 3160.HMWWB | 931164 | H14635-005 |
| 3160.HMWGBR | 932963 | H26793-005 |
| 3160.HMWG.R | 936208 | H45005-005 |
| 3160.NGWG.R | 936209 | H45012-005 |
| 3160.NGWGBR | 936786 | H45026-002 |
| 3160.NGWG.B | 937222 | H73448-002 |
| 3160.HMWWB.R | 937299 | H54442-004 |
| 3160.NGWWB.R | 937300 | H54443-004 |
| 3160.HMWNBG | 946856 | H95522-003 |
| 3160.NGWNBG | 946857 | H95523-003 |

PCN Revision History:

Date of Revision:

December 22, 2016

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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